

10/076, 244

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|--|---|------------------|
| 1 | 5 | ((polyacetylene (polyparaphenylene adj vinylene) ppv polyaniline) near4 dope\$2) and @ad<20000707 and (polymer near3 (plug ball bump)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/01 15:31 |
| 2 | 2 | ("4692225").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/01 15:32 |
| 3 | 1 | ((("4692225").PN.) and dope\$2 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/01 15:32 |
| - | 12 | ((("5923955") or ("5891756") or ("5795818") or ("5904859") or ("5767009") or ("5804876")).PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/01 12:34 |
| - | 0 | ((nickel adj carbonyl) nico4) and @ad<20020213 and ((polymer epoxy dielectric) adj plug) and (semiconductor chip die dice ic (integrated adj circuit)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/24 15:33 |
| - | 1009 | ((nickel adj carbonyl) nico4) and @ad<20020213 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/24 15:33 |
| - | 159 | ((((nickel adj carbonyl) nico4) and @ad<20020213) and (semiconductor chip die dice ic (integrated adj circuit)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/24 15:34 |
| - | 0 | (((((nickel adj carbonyl) nico4) and @ad<20020213) and (semiconductor chip die dice ic (integrated adj circuit))) and ((copper cu) near3 (bump ball)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/24 15:34 |
| - | 159 | ((((nickel adj carbonyl) nico4) and @ad<20020213) and (semiconductor chip die dice ic (integrated adj circuit)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/24 17:07 |
| - | 2560 | ((438/108) or (257/778)).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/24 17:08 |
| - | 165 | ((((438/108) or (257/778)).CCLS.) and @ad<20020213 and ((ball bump) near3 (polymer epoxy)) and conductive | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/25 12:01 |
| - | 165 | ((((438/108) or (257/778)).CCLS.) and @ad<20020213 and ((ball bump) near3 (polymer epoxy)) and conductive | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/02/25 12:02 |

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|---|----|--|---|------------------|
| - | 17 | (polyacetylene (polyparaphenylene adj vinylene) ppv polyaniline) and @ad<20000707 and (polymer near3 (plug ball bump)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/03/01 15:26 |
|---|----|--|---|------------------|